IEEE RAO R. TUMMALA ELECTRONICS PACKAGING AWARD

RECIPIENTS

(Formerly the IEEE Electronics Packaging Award)

2024 – MADHAVAN SWAMINATHAN Department Head Electrical Engineering & Director, CHIMES (an SRC JUMP 2.0 Center), Pennsylvania State University, University Park, PA, USA	“For contributions to semiconductor packaging and system integration technologies that improve the performance, efficiency, and capabilities of electronic systems.”
2023 – GUOQI (KOUCHI) ZHANG Professor, Delft University of Technology, Delft, The Netherlands	“For scientific and technological leadership in “More than Moore” (MtM) packaging, co-designing, and reliability.”
2022 – DOUGLAS C.H. YU Vice President, TSMC, Hsinchu, Taiwan	“For contributions to the development of advanced packaging technologies and their implementation in high-volume manufacturing.”
2021 – CHIN C. LEE Retired Professor, University of California, Irvine, California, USA	“For contributions to new silver alloys, new bonding methods, flip-chip interconnect, and education for electronics packaging.”
2020 – MITSUMASA KOYANAGI Senior Research Fellow, Tohoku University, Sendai, Miyagi, Japan	“For pioneering contributions leading to the commercialization of 3D wafer and die level stacking packaging.”
AND	
PETER RAMM Head of Strategic Projects, Fraunhofer EMFT, Bavaria, Germany	
2019 – EPHRAIM SUHIR Professor, Portland State University, Portland, Oregon, USA	“For seminal contributions to mechanical reliability engineering and modeling of electronic and photonic packages and systems.”
2018 – WILLIAM CHEN Fellow of ASE Group, Sunnyvale, California, USA	“For contributions to electronic packaging from research and development through industrialization, and for his leadership in strategic roadmapping efforts.”
2017 – PAUL S. HO Professor, The University of Texas at Austin, Austin, Texas, USA	“For contributions to the materials science of packaging and its impact on reliability, specifically in the science of electromigration.”
AND	

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KING-NING TU
Distinguished Professor, Department of Material Science & Engineering, University of California at Los Angeles, Los Angeles, California, USA

2016 – MICHAEL PECHT
Director, Center for Advanced Life Cycle Engineering, University of Maryland, College Park, Maryland, USA

"For visionary leadership in the development of physics-of-failure-based and prognostics-based approaches to electronic packaging reliability."

2015 – NASSER BOZORG-GRAYELI
President Technology and Manufacturing Group, Intel Corporation, Tempe, Arizona, USA

"For contributions to the advancement of microelectronic packaging technology, manufacturing, and semiconductor ecosystems."

2014 – AVRAM BAR-COHEN
Distinguished University Professor of Mechanical Engineering, University of Maryland, College Park, Maryland, USA

"For contributions to thermal design, modeling, and analysis, and for original research on heat transfer and liquid-phase cooling."

2013 – JOHN LAU
ITRI Fellow, Industrial Technology Research Institute (ITRI), Hsinchu, Taiwan

"For contributions to the literature in advanced solder materials, manufacturing for highly reliable electronic products, and education in advanced packaging."

2012 – MAURO WALKER
Senior Vice President and Director of Manufacturing, Motorola (Retired), Ocean Ridge, FL, USA

"For advancing electronic manufacturing, technology and packaging worldwide through technical innovation and cooperative leadership in industry, government, academia and professional organizations."

2011 – RAO R. TUMMALA
Endowed Chair Professor, Georgia Institute of Technology, Packaging Research Center, Atlanta, GA, USA

"For pioneering and innovative contributions to package integration research, cross-disciplinary education and globalization of electronic packaging."

2010 – HERBERT REICHL
Full Professor at Faculty IV Technische Univ Berlin Berlin, Germany

"For contributions to the integration of reliability in electronic systems, and leadership in research and education in electronic packaging."

2009 – GEORGE G. HARMAN
NIST Scientist Emeritus

"For achievements in wire bonding technologies."

Gaithersburg, MD, USA

2008 – KARL PUTTLITZ SR.
President, Puttlitz Engineering Consultancy, Wappingers Falls, NY USA
AND
PAUL A. TOTTA
Retired, IBM East Fishkill Facility, East Fishkill, NY, USA

"For pioneering achievements in flip chip interconnection technology and for semiconductor devices and packages"

2007 – DIMITRY GRABBE
Worcester Polytechnic Institute
Worcester, MA

"For contributions to the fields of electrical/electronic connector technology, and development of multi-layer printed wiring boards."

2006 – C. P. WONG
Regent's Professor at Georgia Institute of Technology, Atlanta, GA

"For contributions in advanced polymeric materials science and processes for highly reliable electronic packages."

2005 – YUTAKA TSUKADA
Manager of Packaging Technology Development
Kyocera SLC Technologies Corp
Shiga-Ken, Japan

"For pioneering contributions in micro-via technology for printed circuit boards, and for extending the feasibility of the direct flip-chip attachment process."

2004 – JOHN W. BALDE
Senior Consultant
Interconnection Decision Consulting
Flemington, NJ

"For lifetime contributions to tantalum film technology and the introduction of new electronic packaging technology to development and manufacturing."